

AMENDMENTS TO THE CLAIMS

1. (original) A method of sorting dice by speed comprising:  
identifying good and bad dice while the dice are part  
of a wafer;  
making a wafer map of speed grades of the good dice;  
dicing the wafer;  
for a wafer having first and second speed grades  
different from each other:  
filling an order for a first package type and  
the first speed grade by attaching dice of  
the first speed grade to packages of the  
first package type; and  
placing dice of the second speed grade into  
another location; and  
completing the process of packaging.
2. (original) The method of sorting dice of Claim 1 wherein  
the step of placing dice of the second speed grade into another  
location comprises:  
filling an order for a second package type and the  
second speed grade by attaching dice of the second  
speed grade to packages of the second package  
type.
3. (original) The method of sorting dice of Claim 1 wherein  
the step of placing dice of the second speed grade into another  
location comprises:  
placing dice of the second speed grade into a carrier  
for storage until the second speed grade is  
ordered.
4. (original) The method of claim 1 comprising the further  
step of:  
marking each of the packages with a mark indicating the  
first speed grade.

5. (original) The method of claim 1 wherein the steps of attaching dice are performed by a programmed die attach machine that uses the speed grades in the wafer map.

6. (original) The method of claim 5 wherein the die attach machine further transfers some of the dice to a storage location unpackaged.

7. (original) The method of Claim 5 wherein the die attach machine fills part of an order by attaching dice that have been stored in a storage location to packages of the first package type.

8 - 10. (canceled)